





100V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = 25°C
-100V	350mΩ @ V _{GS} = -10V	-1.6
	450mΩ @ V _{GS} = -6.0V	-1.4

Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor control
- **DC-DC** Converters
- Power management functions
- Uninterrupted power supply

Features and Benefits

- Fast switching speed
- Low gate drive
- Low input capacitance
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23-6 •
- Case Material: Molded Plastic, UL Flammability Classification • Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Weight: 0.018 grams (approximate)



SOT23-6



Top View





Equivalent Circuit

Ordering Information

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMP10A17E6TA	See below	7	8	3,000

Marking Information



1A17 = Product Type Marking Code



Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source voltage			V _{DSS}	-100	V
Gate-Source voltage			V _{GS}	±20	V
		(Note 2)		-1.6	
Continuous Drain current	$V_{GS} = 10V$	$T_{A} = 70^{\circ}C$ (Note 2)	ID	-1.3	А
		(Note 1)		-1.3	
Pulsed Drain current	V _{GS} = 10V	(Note 3)	I _{DM}	-7.7	А
Continuous Source current (Body diode) (Note 2)		(Note 2)	Is	-2.1	А
Pulsed Source current (Body diode) (Note3)		I _{SM}	-7.7	А	

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
Power dissipation	(Note 1)		1.1 8.8	W	
Linear derating factor	(Note 2)	— P _D	1.7 13.7	mW/°C	
Thermal Registerion Junction to Ambient	(Note 1)		113	°C/W	
Thermal Resistance, Junction to Ambient	(Note 2)	R _{θJA}	73	-0/10	
Operating and storage temperature range		T _J , T _{STG}	-55 to 150	۵°C	

Notes: 1. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

2. Same as note (1), except the device is measured at t \leq 5 sec.

3. Same as note (1), except the device is pulsed with D= 0.02 and pulse width 300 µs. The pulse current is limited by the maximum junction temperature.



Thermal Characteristics







Characteristic	Symbol	Min	Тур	Max	Unit	Test	Condition	
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV _{DSS}	-100			V	I _D = -250μA, V _{GS} = 0V		
Zero Gate Voltage Drain Current	I _{DSS}	_		-0.5	μA	V _{DS} = -100V, V _{GS} = 0V		
Gate-Source Leakage	I _{GSS}	_		±100	nA	V _{GS} = ±20V, V _{DS} = 0V		
ON CHARACTERISTICS								
Gate Threshold Voltage	V _{GS(th)}	-2.0		-4.0	V	I_{D} = -250 μ A, V_{D}	os= V _{GS}	
Static Drain-Source On-Resistance (Note 4)	Bee (ev)			0.350	Ω	V _{GS} = -10V, I _D = -1.4A		
	R _{DS} (ON)	_		0.450	10	V_{GS} = -6V, I_{D} =	-1.2A	
Forward Transconductance (Notes 4 & 5)	g fs	_	2.8		S	V _{DS} = -15V, I _D = -1.4A		
Diode Forward Voltage (Note 4)	V _{SD}	_	-0.85	-0.95	V	I _S = -1.7A, V _{GS} = 0V		
Reverse recovery time (Note 5)	t _{rr}		33		ns			
Reverse recovery charge (Note 5)	Qrr	_	48		nC			
DYNAMIC CHARACTERISTICS (Note 5)								
Input Capacitance	C _{iss}	_	424		pF	−V _{DS} = -50V, V _{GS} = 0V −f= 1MHz		
Output Capacitance	C _{oss}	_	36.6		pF			
Reverse Transfer Capacitance	C _{rss}	_	29.8	—	pF			
Total Gate Charge (Note 6)	Qg	_	7.1	—	nC	V _{GS} = -6.0V		
Total Gate Charge (Note 6)	Qg	_	10.7		nC		V _{DS} = -50V	
Gate-Source Charge (Note 6)	Q _{gs}		1.7		nC	V _{GS} = -10V	I _D = -1.4A	
Gate-Drain Charge (Note 6)	Q _{gd}	_	3.8		nC			
Turn-On Delay Time (Note 6)	t _{D(on)}	_	3.0		ns	V _{DD} = -50V, V _{GS} = -10V		
Turn-On Rise Time (Note 6)	tr	_	3.5		ns			
Turn-Off Delay Time (Note 6)	t _{D(off)}	_	13.4		ns	I _D = -1A, R _G ≅ 6	ο.0Ω	
Turn-Off Fall Time (Note 6)	t _f	_	7.2	_	ns	1		

4. Measured under pulsed conditions. Pulse width $\leq 300 \mu s;$ duty cycle $\leq 2\%$

For design aid only, not subject to production testing.
Switching characteristics are independent of operating junction temperatures.

Notes:



Typical Characteristics





Typical Characteristics - continued



Test Circuits



Basic gate charge waveform



Gate charge test circuit



Switching time waveforms



Switching time test circuit



Package Outline Dimensions



DIM	Millin	neters	Inch	nes
	Min	Max	Min	Max
Α	0.90	1.45	0.354	0.0570
A1	0.00	0.15	0.00	0.0059
A2	0.90	1.30	0.0354	0.0511
b	0.20	0.50	0.0078	0.0196
С	0.09	0.26	0.0035	0.0102
D	2.70	3.10	0.1062	0.1220
E	2.20	3.20	0.0866	0.1181
E1	1.30	1.80	0.0511	0.0708
L	0.10	0.60	0.0039	0.0236
е	0.95 REF		0.0374 REF	
e1	1.90 REF		0.0748	REF
θ	0°	30°	0°	30°

Suggested Pad Layout





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